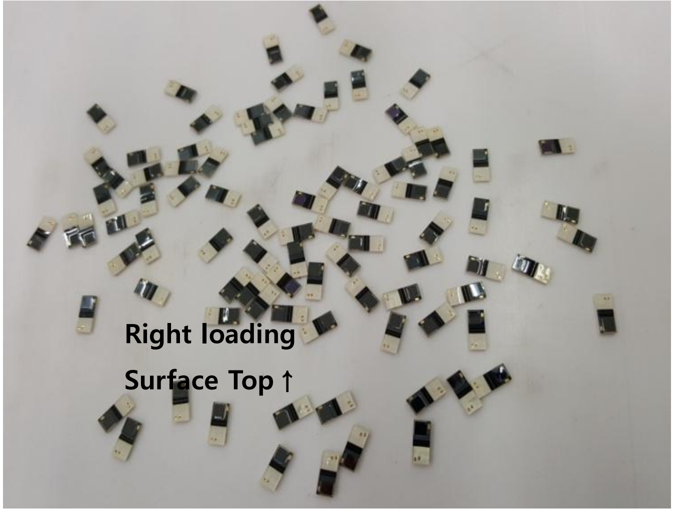
prepared by shoon Han 9 Jan 2017

Prebake Guide

Please prebake **2hours at 150C** before reflow or **1hour at 125C** before manual soldering to make sure moisture free.

Loading condition

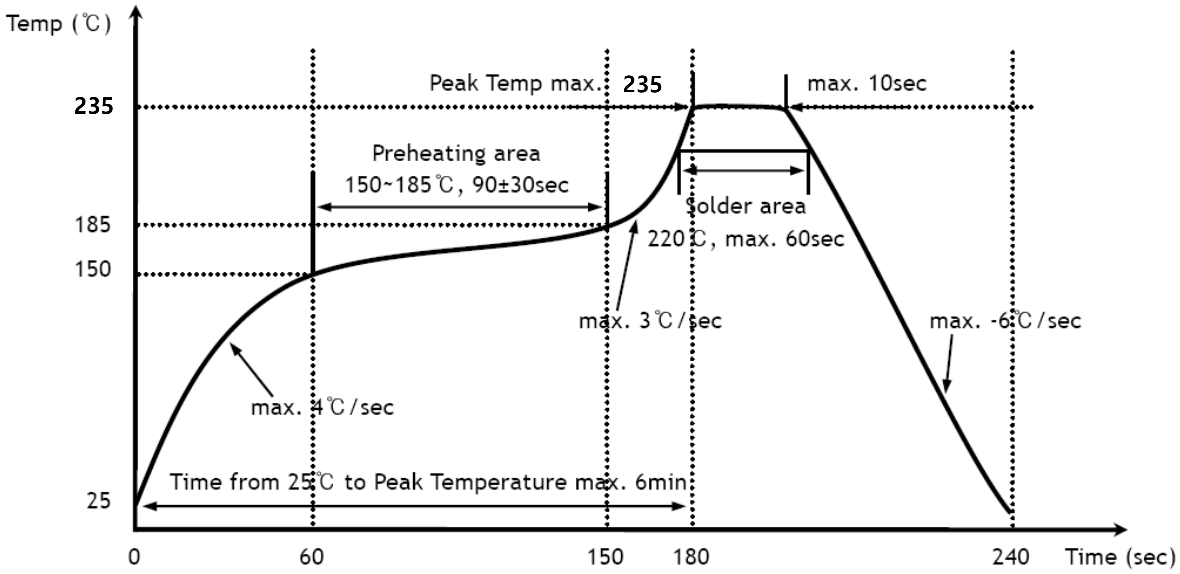
1. Load DCM03 surface upward in a clean, dry, shallow container so that the package bodies do not overlap each other and do not surface be downward.
2. Not sooner than 15 minutes and not longer than 1 hour after removal from the bake oven, subject the units to the appropriate reflow or manual soldering condition.



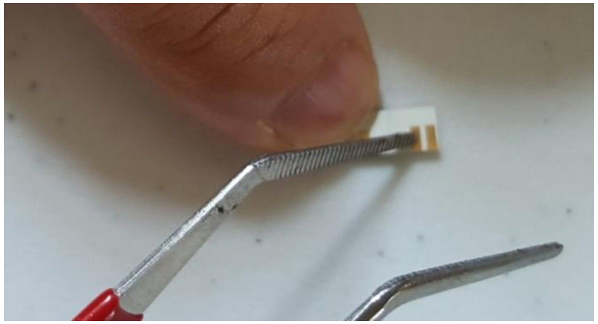
Reflow Guide

Recommended Reflow Soldering Temperature Profile

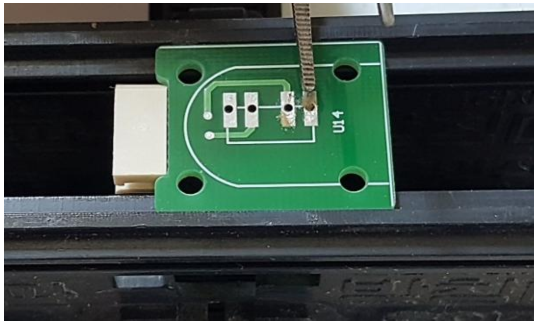
Soldering 235°C within 10sec
Gradual cooling to avoid quenching



Manual Soldering Guide



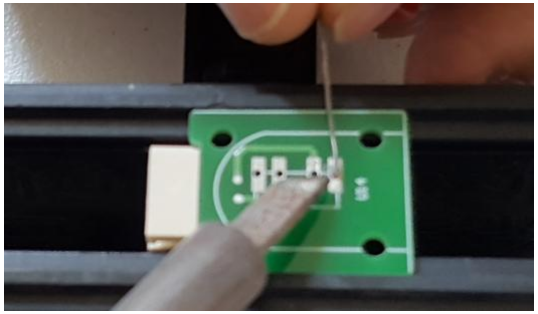
1. Flux wetting DCM03 pads



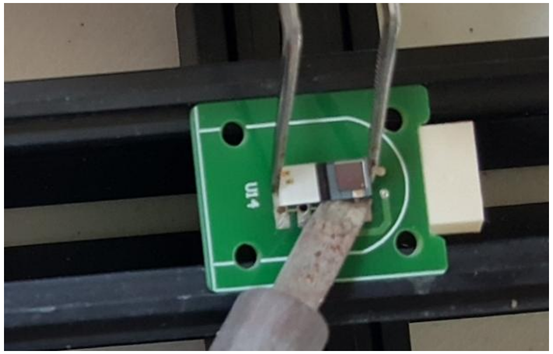
2. Flux wetting PCB pads

3. Knife shape solder probe

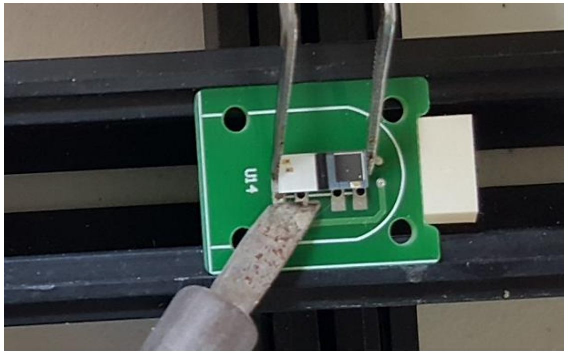
4. Solder wetting DCM03 pads



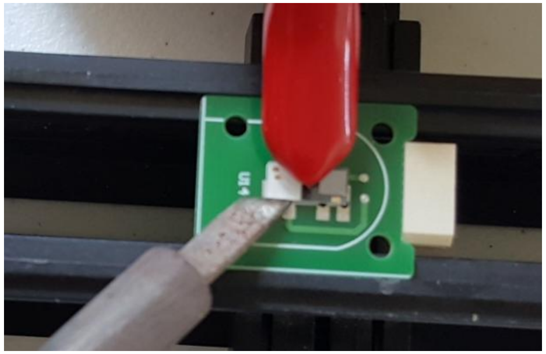
5. Solder wetting PCB pads



6. Heating side A



7. Heating side B



8. Heating & pressing
for planarization